

# Product data sheet

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Semiconductor Compiance

## **FEATURES**

- Low forward voltage
- High current capability
- High forward surge capability
- Low power losses, High efficiency
- Guarding for over voltage protection

## **APPLICATIONS**

Low VF Schottky barrier rectifier are designed for high freqency, miniature switched mode power supplies such as adapters, lighting and on-board DC/DC conerters

Primary Characteristic		
lo	2*5A	
V <sub>RRM</sub>	60V	
I <sub>FSM</sub>	190A	
VF	0.59V	
TJmax	<b>150</b> ℃	
Assembly code	AC	

## **MECHANICAL DATA**

- Case: Molded plastic
- Polarity: As marked
- Mounting Position: Any
- $\bullet \, \textbf{Molded Plastic:} \, UL Flammability Classification Rating 94V-0$
- $\bullet \, Lead free \, in \, compliance \, with \, EU \, RoHS \, 2011/65/EU \, directive$
- Solder bath temperature 275  $^\circ\!\!\mathrm{C}$  maximum,10s per JESD 22-B106

Characteristics	Symbol	Value	Unit
Maximum Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	60	V
Working Peak Reverse Voltage	V <sub>RWM</sub>	60	V
Maximum DC Blocking Voltage	V <sub>DC</sub>	60	V
Maximum Avenue Forward Destified Current Per Leg		5	•
Maximum Average Forward Rectified Current Total	Io	10	— A
Peak Forward Surge Current, 8.3 ms Single Half Sine-wave	e I <sub>FSM</sub>	190	A
Operating Temperature Range	TJ	150	°C
Storage Temperature Range	T <sub>STG</sub>	-40 to +150	°C
TypicalThermalResistance(Note1)			
TO-220AB,TO-263,TO-252	R <sub>0 IC</sub>	2	°C/W
TO-220F	<i>v</i> -	4	

Note1: Thermal resistance from Junction to case per leg mounted on heatsink.

Electrical Characteristics (Per	<sup>-</sup> Leg) unless o	otherwise s	specified		
Characteristics		Symbol	Va	ue	Unit
Forward Voltage Drop(Note2)			Тур.	Max.	
	TA=25°C	] [	0.53	-	
at I <sub>F</sub> =2A	TA=125°C	] [	0.47	-	
at I <sub>F</sub> =3A	TA=25°C	V <sub>F</sub>	0.59	-	V
	TA=125°C	] [	0.52	-	
at I <sub>F</sub> =5A	TA=25°C	] [	0.69	0.75	
	TA=125°C	] [	0.59	-	
Maximum Reverse Current at V <sub>R</sub> =60V	TA=25°C		2	50	μA
	TA=125°C	- I <sub>R</sub>	1.5	-	mA

Note2:Pulse test: 300 µs pulse width, 1 % duty cycle



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## SCHOTTKY BARRIER RECTIFIER



TO-220AB/CT



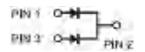
TO-220F/FCT



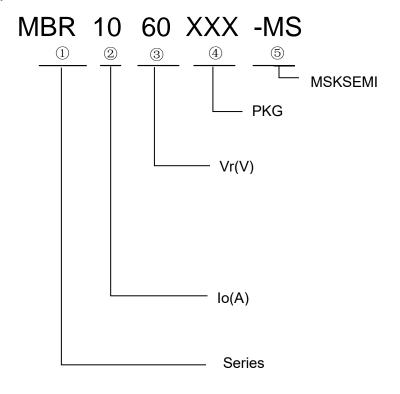
TO-263/DC



TO-252/CS



## **P/N Information**

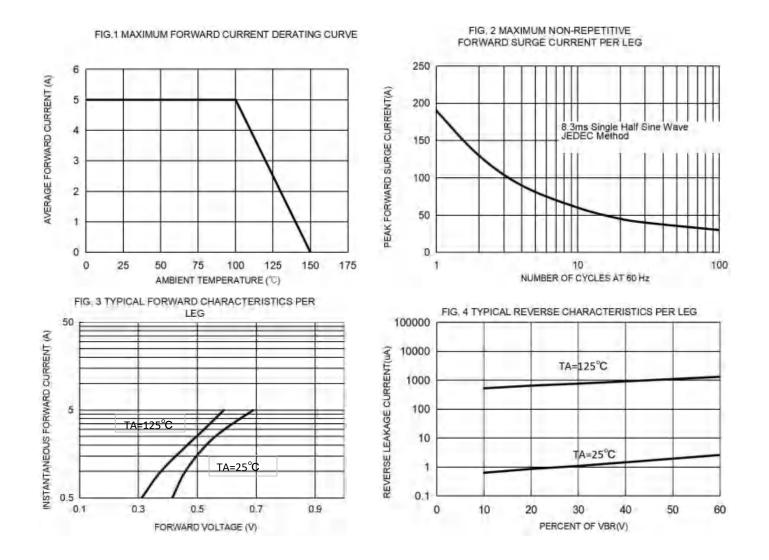


1	2	3	(4)	5
系列	平均整流电流	直流反向耐压	封装	MSKSEMI



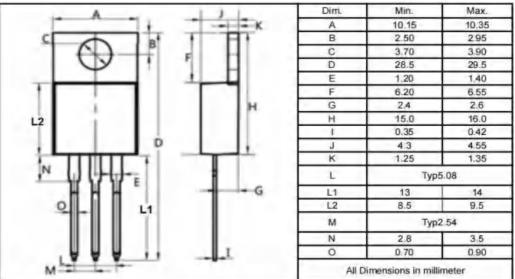
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## RATINGS AND CHARACTERISTICCURVES





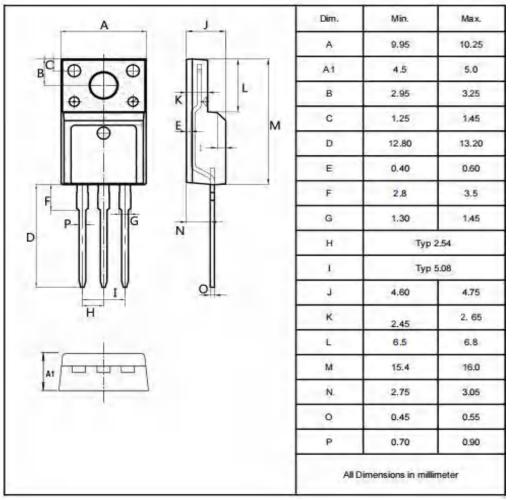
TO-220AB



P/N	PKG	QTY
MBR1060CT-MS	TO-220AB	50pcs/tube 1000pcs/box

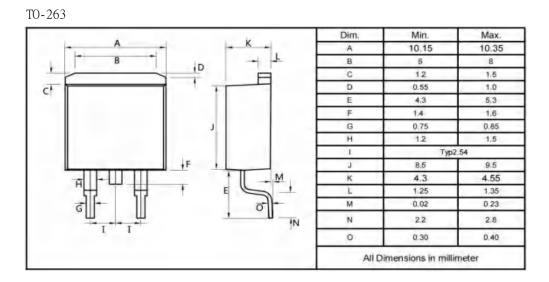


TO-220F



P/N	PKG	QTY
MBR1060FCT-MS	TO-220F	50pcs/tube 1000pcs/box





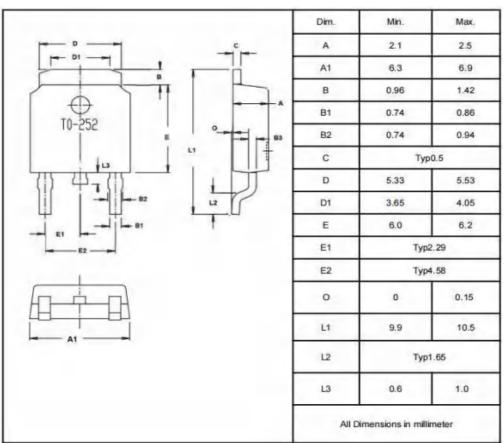
#### **REEL SPECIFICATION**

P/N	PKG	QTY
MBR1060DC-MS	TO-263	50pcs/tube 1000pcs/box

P/N	PKG	QTY
MBR1060DC-R-MS	TO-263	800pcs



TO-252



P/N	PKG	QTY
MBR1060CS-MS	TO-252	2500



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